6089-127 Rev A Heatsink Removal

The thermal foam that is used to provide good heat transfer from active devices to their heatsink has the tendency to "glue" the heatsink to the device. The device or the circuit board can be damaged if the heatsink is just pried off with mechanical force. One could pull the lid off the FPGA or pull the FireFly sockets from the board.

Removal requires that the heatsink be slightly warmed, typically to about 60 degC or 150 degF.

1) Remove all retaining screws and springs. It can be useful to remove the FPGA standoffs.
2) Mask portions of the board that should not be heated. This is to prevent inadvertent damage to parts, fibers, or the board.
3) Use a hot air gun to uniformly warm the heatsink. Periodically try to move the heatsink. At some point it will slide or lift and can be removed.

FireFly Heatsink masked with foil
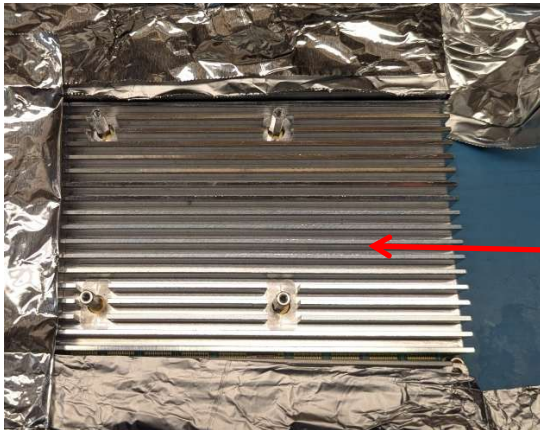
FPGA Heatsink masked with foil
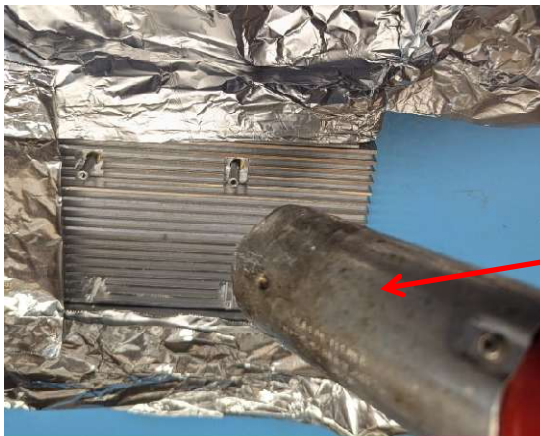
Hotair heatgun used to warm heatsink